



Product Change Notification

Change Notification #: 116732 - 00
Change Title: Select Intel® Core™ Processors,
Intel® Pentium® Processors,
Intel® and Celeron® Processors ,
PCN 116732-00, Manufacturing Site,
Notification to Customers for Addition of
Factory Assembly/Test Site/Finished Goods
site
Date of Publication: January 30, 2019

Key Characteristics of the Change:
Manufacturing Site

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	March 15, 2019
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Description of Change to the Customer:

In order to ensure a continuous supply of the Intel Processors listed in the "Products Affected" Table below, Intel will be adding Vietnam as a qualified site to do any of the Manufacturing Assembly, Test or Finish processes. Vietnam may have been qualified already to do Test/Finish in some cases, but now will do Assembly as well. The new manufacturing site Vietnam has been certified equivalent (form, fit, function, and reliability) for the affected products and technologies of this change.

Any of the manufacturing processes can be done in Vietnam, Malaysia or China. Therefore, depending on where Assembly is done, customers may see a change to the value displayed on the Shipping Box labels for Country of Origin (COO).

See Samples below (pictures for example only)

(P) CUST PROD: (1B) BOX: RLX00037

(V) SUPPLIER: 04195 INTEL

(1P) IPN: INTEL PRODUCT NAMEXX

(S) SPEC: S 1234 (30P) MM#: 123456

(1T) LOT: FPO NUMBER (Q) QTY: 12345 (9D) DATE: YYWW

(1T) LOT: (Q) QTY: (9D) DATE:

RoHS COMPLIANT, e1

MAX REFLOW 260 °C
TEMP
LEVEL 3 HOURS 168
BAG SEAL DATE 03JUN14

ASSEMBLED IN VIETNAM

(P) CUST PROD: (1B) BOX: RLP00008

(V) SUPPLIER: 04195 INTEL

(1P) IPN: INTEL PRODUCT NAMEXX

(S) SPEC: S 1234 (30P) MM#: 123456

(1T) LOT: FPO NUMBER (Q) QTY: 12345 (9D) DATE: YYWW

(1T) LOT: (Q) QTY: (9D) DATE:

RoHS COMPLIANT, e1

MAX REFLOW 260 °C
TEMP
LEVEL 3 HOURS 168
BAG SEAL DATE 09DEC08

ASSEMBLED IN MALAYSIA

(P) CUST PROD: (1B) BOX: RLX00036

(V) SUPPLIER: 04195 INTEL

(1P) IPN: INTEL PRODUCT NAMEXX

(S) SPEC: S 1234 (30P) MM#: 123456

(1T) LOT: FPO NUMBER (Q) QTY: 12345 (9D) DATE: YYWW

(1T) LOT: (Q) QTY: (9D) DATE:

RoHS COMPLIANT, e1

MAX REFLOW 260 °C
TEMP
LEVEL 3 HOURS 168
BAG SEAL DATE 03JUN14

ASSEMBLED IN CHINA

Customer Impact of Change and Recommended Action:

Intel anticipates no impact to customers for this change. Customers should notify their receiving department of the additional country which will be providing the Assembly/Test/Finish on the products. It's possible that Customers may receive a mix of material from multiple sites consisting of China, Malaysia, or Vietnam.

Customers may contact their Intel Field Sales Representative or the contacts listed on the last page of this Product Change Notification appropriate to your geo with questions.

Products Affected / Intel Ordering Codes:

Marketing Name	Processor#	Stepping	Product Code	S-Spec	MM#
Intel® Core™ i7-7600U Processor	I7-7600U	H0	FJ8067702739628	S R33Z	953350
Intel® Core™ i5-7300U Processor	I5-7300U	H0	FJ8067702739633	S R340	953351
Intel® Core™ i7-7500U Processor	I7-7500U	H0	FJ8067702739740	S R341	953352
Intel® Core™ i5-7200U Processor	I5-7200U	H0	FJ8067702739739	S R342	953353
Intel® Core™ i3-7100U Processor	I3-7100U	H0	FJ8067702739738	S R343	953354
Intel® Pentium® Processor 4415U	4415U	H0	FJ8067702739932	S R348	953359
Intel® Celeron® Processor 3865U	3865U	H0	FJ8067702739933	S R349	953360
Intel® Celeron® Processor 3965U	3965U	H0	FJ8067702739934	S R34A	953361
Intel® Core™ i3-7130U Processor	I3-7130U	H0	FJ8067702739765	S R3JY	958406
Intel® Core™ i7-8650U Processor	I7-8650U	Y0	FJ8067703281718	S R3L8	959152
Intel® Core™ i5-8350U Processor	I5-8350U	Y0	FJ8067703282016	S R3L9	959155
Intel® Core™ i5-8250U Processor	I5-8250U	Y0	FJ8067703282221	S R3LA	959160
Intel® Core™ i7-8550U Processor	I7-8550U	Y0	FJ8067703281816	S R3LC	959163
Intel® Core™ i3-7020U Processor	I3-7020U	Y0	FJ8067703282620	S R3LD	959164
Intel® Core™ i3-7020U Processor	I3-7020U	H0	FJ8067702739769	S R3TK	961968
Intel® Core™ i3-8130U Processor	I3-8130U	Y0	FJ8067703282227	S R3W0	963178
Intel® Pentium® Processor 4417U	4417U	Y0	FJ8067703282813	S RESH	984527
Intel® Celeron® Processor 3867U	3867U	Y0	FJ8067703283011	S RESK	984528

PCN Revision History:

Date of Revision:

January 30, 2019

Revision Number:

00

Reason:

Originally Published PCN



Product Change Notification

116732 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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